#### 外部委託業者の募集

References: IO/MS/25/YSA/SA

#### "Splicer Assembly"

(スプライサー組み立て)

IO 締め切り 2025 年 2 月 24 日(月)

#### ○はじめに

スプライシングデバイス (SD) は、超伝導磁石からの配線をトカマクの壁にあるコネクタに信号を送るケーブルに接続する高電圧 (HV) ジョイントです。

スプライシングデバイスの組み立て過程では、いくつかの作業を注意深く行う必要があります。SD のいわゆる HV パッシェンテストは、組み立ての品質が正しいかどうかを判定するものです。

スプライサー組み立ての主な役割は、SD の個別の HV パッシェンテストを行えるようにし、組み立て中の SD の損傷リスクを軽減することです。HV パッシェンテストでは、スプライシング組み立て内部の圧力を 1e-2[mbar]まで下げる必要があります。

IO は、必要なすべての機能を組み込んだスプライサーアセンブリの初期設計を作成しました。この設計は、供給者と共有され、改善や調整のために活用されます。

#### 図 1.1 スプライシングデバイスとスプライサー組み立ての概要

(詳細は英文技術仕様書を参照下さい)

#### ○スプライサーの特徴

SD の組み立てミスや取り扱いミス、ケーブル/ワイヤーの絶縁損傷が磁石システムに与えるリスクを 軽減するために、以下の特徴をスプライサー設計に組み込む必要があります。

#### HV パッシェンテスト用の真空チャンバー機能

HV パッシェンテストは、HV 絶縁の不良を検出するためのものです。このテスト中、チャンバー内の真空圧力が変化します。もし絶縁に不良があれば、小電流の真空アークが発生することがあり、これは測定機器によって検出できます。

ノズルとポンピングシステムへのインターフェースは、初期の IO 設計では取り外し可能ですが、これは必須ではありません。

図 1.4: ポンピングシステム接続用ノズルのビュー。

#### ワイヤー側

図 1.6:ケーブル側のシーリングチャンバーの断面図

(詳細は英文技術仕様書を参照下さい)

EMC シールドと GND シールドポテンシャルトランジション

ワイヤー側

金属製のエッジクリップがワイヤーを円形に配置し、HV ワイヤーシールドのポテンシャルをスプライサーのケースに導きます。金属製ケースはSD を完全に包み込みます。

## 図 1.7: エッジクリップとスプライサーケースへの HV ワイヤーシールド接続 (詳細は英文技術仕様書を参照下さい)

#### ケーブル側

ケーブル側では、溝がケーブルシールドを SD ケースにクランプするために使用されます。この溝は金属製で、スプライサー本体と接触しています。

図 1.8: 専用溝にクランプされたケーブルシールド

(詳細は英文技術仕様書を参照下さい)

このシステムは、HV ワイヤー側から HV 真空ケーブルへの GND シールドポテンシャルの継続性を確保します。

#### ストレインリリーフ

ワイヤー側

エッジクリップがワイヤーを円形に配置し、ストレインリリーフ機能はケーブル側ほど重要ではありません。

図 1.9: HV ワイヤー側のストレインリリーフ

(詳細は英文技術仕様書を参照下さい)

#### ケーブル側

ケーブルの外ジャケットがチャンバーに入る際、ケーブルの曲げに対する弱点が保護されます。

図 1.10:ケーブル側のストレインリリーフ

(詳細は英文技術仕様書を参照下さい)

#### SD の重量による恒常的な荷重

シールドクランプ用のブラケットの直径は、シリコン製ストレインリリーフと接触するように調整されており、SD の垂直位置で荷重が停止します。

図 1.11:垂直位置で SD の荷重を停止させるメカニズム

(詳細は英文技術仕様書を参照下さい)

#### ○ターゲット価格とコスト設計の最適化

ITER 組織 (IO) は、スプライサーアセンブリの初期設計をすでに行っています。スプライサー組み立てのシリーズ生産を開始する前に、設計は供給者の知識を活用して最適化され、IO のターゲット価格に合致させる必要があります。これを「コスト設計最適化」と呼びます。

#### ○暫定的な実施スケジュール

契約は、以下に示すように2つの段階/フェーズ/部分に分けて計画されています。製造は、To-Cost

Design Optimization の成果物に対する IO の検証後にのみ開始できます。

(詳細は技術仕様書を参照してください)

#### ○追加の注意事項および免責事項

- 調査に関する質問がある場合は、カバーレターに記載された連絡先にメールで送信してください。受け取った質問とその回答は、質問者を特定しない形で公開される場合があります。
- この市場調査に関する追加情報や修正があった場合、それらは同じウェブページで公開されます。
- 本市場調査に提供された情報は暫定的なものであり、変更される可能性があります。
- 本調査で提供された情報に関連するすべての知的財産権およびその他の権利は、IO に帰属します。本調査に参加する者および情報を閲覧する者は、調査への回答準備の目的のみで取得した情報を使用することが許可されており、その他の目的で使用することはできません。
- 本調査への参加は、将来の調達プロセスに自動的に参加資格を与えるものではありません。将 来の調達手続きへの資格は未定です。

【※ 詳しくは添付の英語版技術仕様書「Splicer Assembly - Technical inputs for Market Survey」をご 参照ください。】

ITER 公式ウェブ <a href="http://www.iter.org/org/team/adm/proc/overview">http://www.iter.org/org/team/adm/proc/overview</a> からもアクセスが可能です。

「核融合エネルギー研究開発部門」の HP: http://www.fusion.qst.go.jp/ITER/index.html では ITER 機構からの各募集(IO 職員募集、IO 外部委託、IO エキスパート募集)を逐次更新しています。ぜひご確認ください。

## イーター国際核融合エネルギー機構からの外部委託 に関心ある企業及び研究機関の募集について

### <ITER 機構から参加極へのレター>

以下に、外部委託の概要と要求事項が示されています。参加極には、提案された業務に要求される能力を有し、入札すべきと考える企業及び研究機関の連絡先の情報を ITER 機構へ伝えることが求められています。このため、本研究・業務に関心を持たれる企業及び研究機関におかれましては、応募書類の提出要領にしたがって連絡先情報をご提出下さい。



To: Potential Suppliers

Ref: IO/MS/25/YSA/SA

Subject: Letter of Invitation for the Market Survey on "Splicer Assembly"

Dear Madam/Sir,

The ITER Organization (IO) launches a Market Survey and requests information from companies having the interest, knowledge, and capacity related to **the Splicer Assembly procurement.** With this letter, we invite all potential companies, institutions, or entities from ITER Member States to participate to this Market Survey.

The main purposes of this Market Survey are to incorporate the recent market situation into the procurement conditions as well as into the technical specifications and to prepare the budget baseline for the contract(s).

china

india

japan

korea

russia

usa

Please note that this is not a Call for Nomination request, and all information including cost estimation to be collected are considered only as referential and non-binding basis. Therefore, we would greatly appreciate your feedback, which will help the IO to better understand the real situation of the industry.

You will find enclosed:

Annex I: Technical Inputs for Market Survey

- Appendix-1: Preliminary Design Drawings of Splicer Assembly
- Appendix-2: Preliminary Design 3D model data of Splicer Assembly

Annex II: Request for Information (RFI) Questionnaire

Please return a completed questionnaire using Annex II, <u>no later than 24 February 2025</u>, to the following email address <u>Yuki.Suyama@iter.org</u> with CC to <u>Guillaume.Retaillaud@iter.org</u>.

Thanks in advance for your participation and co-operation.

Yours faithfully,

William DE CAT
Procurement Division
Operations Manager
Procurement Division

# Splicer Assembly - Technical inputs for Market Survey

## 1. Introduction

The Splicing Device (SD) is a high-voltage (HV) joint that connects wires from a superconducting magnet to the cable transmitting signals to the connector at Tokamak's wall.

During the assembly process of the splicing device, several activities demand a significant amount of care and attention. The so called HV Paschen test of the SD will determine the correctness of the assembly quality.

The primary role of the Splicer Assembly is to permit the individual HV Paschen test of the SD and mitigate the risk of SD damage during assembly. HV Paschen test requires pressures levels inside the Splicing assembly down to 1e<sup>-2</sup> [mbar].

IO has generated an initial design of the Splicer Assembly, incorporating all necessary features. This design will be shared with the supplier for potential enhancements and adjustments.

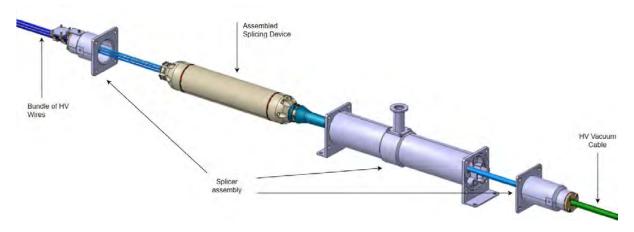


Figure 1.1 Overview of the Splicing Device and Splicer assembly.

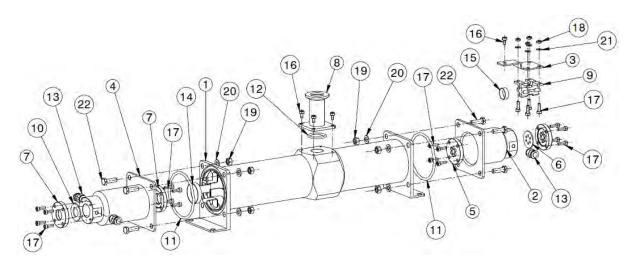


Figure 1.2 Detail of the preliminary IO design of the Splicer.

Item No.	Part Number	Revision	Material	Quantity	Weight
1	SD_SUPPORT#AUUYZ5	A	316L	1	1.207kg
2	RESIN_CHAMBER_HV_WIRES#AUUZ5X	A	316L	1	0.395kg
3	HV_WIRES_SHIELD_CONNECTOR_PLATE#AUUZ72	A	316L	1	0.016kg
4	RESIN_CHAMBER_CABLE#AUUZ3Y	A	316L	1	0.408kg
5	HV_WIRES_GASKET_CAP#AUV4YL	A	316L	2	0.028kg
6	HV_WIRES_GASKET#AUV52H	A	Viton (Fluoro Elastomer)	2	7.559e-004kg
7	CABLE_GASKET_CAP#AUV8LH	B	316L	2	0.025kg
8	SD_SUPPORT_KF16-19-40_NOZZLE#AUV4SM	A	316L	1	0.063kg
	Welded Flange KF 16/19/40				
9	HV_WIRES_SHIELD_CONNECTOR#AUV8HT		316L	1	0.027kg
10	CABLE GASKET#AMWK58		Viton (Fluoro Elastomer)	2	6.011e-004kg
11	SD_O-RING_SUPPORT_DIN56_EP3#AUV4UN	200	-	2	0kg
12	SD_O-RING_KF_NOZZLE_DINT2O-EP2#AUV4WK	222	2	1	0kg
13	PNEUMATIC_CONNECTOR_QSM-M5-6#ANPCR5	5.5.7	4	4	0kg
14	AXOCLAMP_AXCL-02#AMWUN7	+3.4	316L	1	0.002kg
15	CIRCULAR_CLIP_TBD#AMWVAD		Nylon	1	1.262e-004kg
16	CYLINDER_HEAD_SCREW_ISO_4762_M3X6#48SG8X	444	Steel_8.8	5	8.208e-004kg
17	CYLINDER_HEAD_SCREW_ISO_4762_M3X10#3ZNKKX		316L	20	0.001kg
18	HEXAGON_NUT_ISO_4032_M3#YQYV38	AND THE	316L	4	3.953e-004kg
19	HEXAGON_NUT_ISO_4032_M5#YEAQTG	-22	Steel_8.8	8	0.001kg
20	WASHER_ISO_7089_5#VUM5YR		8:	8	0kg
21	WASHER_ISO_7089_3#WAQFHC	***	A2_304L	4	1.185e-004kg
22	HEXAGON BOLT ISO 4017 M5X16#26YGSK		stainless steel	8	0.004kg

Figure 1.3 BOM of components occurring in the preliminary assembly Error! Reference source not found..

## 2. Splicer features

To mitigate the risks to the magnet system that may result from SD assembly errors or mishandling & cables/ wires insulation damage, the features listed below need to be integrated into the Splicer design.

## Vacuum chamber function for a HV Paschen-tightness test

The HV Paschen test enables the detection of failures in HV insulation. During this test, the vacuum pressure inside the chamber is varied. If the insulation is faulty, it may lead to the development of small-current vacuum arcs, which can be detected by the measuring instrument.

Nozzle, interface to the pumping system is removable in the preliminary IO design, but this is not a requirement.

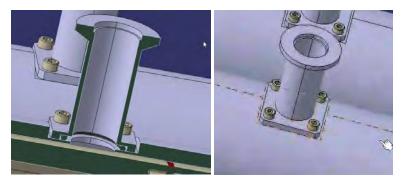


Figure 1.4 View of nozzle for connecting the pumping system.

#### Wires-side

Small, sealing chamber will be filled with a resin through pneumatic fittings. Injection can be made with a syringe. Gaskets on both sides of the sealing chamber will prevent the silicone from leaking. Wires inside the sealing chamber are not shielded.

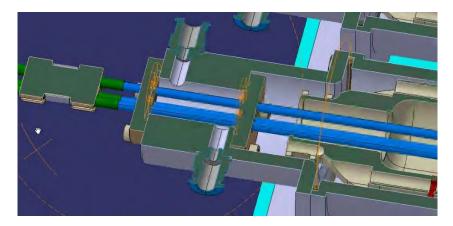


Figure 1.5 Cross-sectional view of the sealing chamber at the HV Wires side.

#### Cable-side

Same principle as for wires-side. The cable enters the chamber with the other jacket.

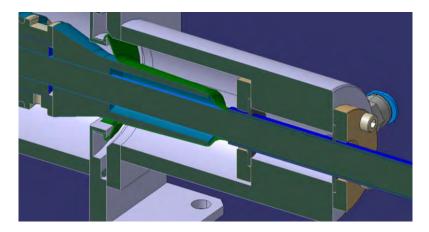


Figure 1.6 Cross-sectional view of the sealing chamber at the cable side.

### EMC screening and GND Shield potential transition

#### On wires-side

A metallic edge clip securely hold wires in circular distribution and brings the HV Wires shield potential to the case of the Splicer, metallic case envelops fully the SD.

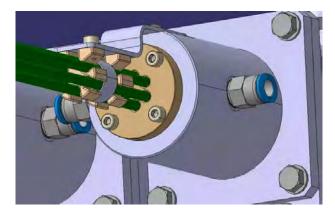


Figure 1.7 HV wires shields connection to the edge clip and the Splicer case.

#### On cable-side

On cable side, a groove will allow to clamp the cable shield to the case of the SD. The groove is metallic and in contact with the Splicer body.

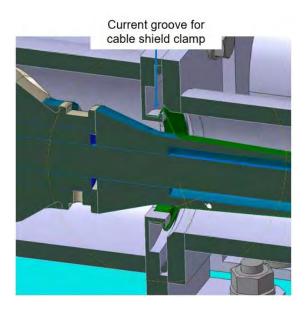


Figure 1.8 Cable shield clamped to the dedicated groove.

This system ensures the continuity of the GND Shield potential from the HV Wires side to the HV Vacuum Cable.

#### Strein relief

#### On wires-side

An edge clip securely hold wires in circular distribution. The strain relief function is less critical on the wire side than on the cable side.

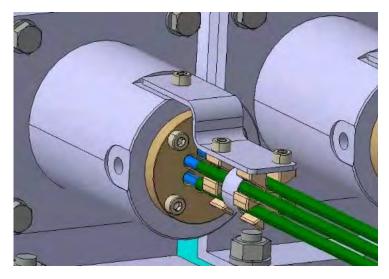


Figure 1.9 Strain relief at the HV Wires side.

#### On cable-side

The outer jacket of the cable enters the chamber, the weak point to cable bending is protected.

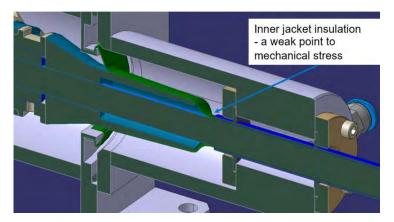


Figure 1.10 Strain relief at the cable side.

## Permanent load due to SD weight

The diameter of the bracket for the shield clamping has been adjusted in order to get in contact with the silicon strain relief and stop the load of the SD in vertical position.

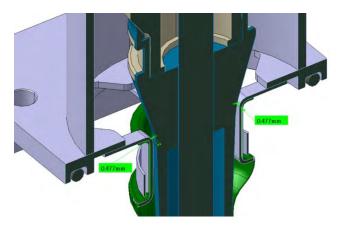


Figure 1.11 Mechanism to stop the load from SD in vertical position.

## 3. Target Price and To-Cost Design Optimization

The ITER Organization (IO) has already carried out a preliminary design of the Splicer Assembly. In prior to start the series production of the Splicer Assemblies, the design still needs to be optimized by the supplier using its knowledge to meet the IO's target price as shown below. This redesign phase is called "To-Cost Design Optimization".

Type of Splice Assembly	Quantity	Target Price
Prototype units	1 unit	Below 1.30kEUR per unit
Pre-series units	18 units	Below 1.30kEUR per unit
Series production	450 units	Below 1.00kEUR per unit

## 4. Tentative Implementation Schedule

The contract is planned to be divided into two stages/phases/parts as shown below. Manufacturing can be commenced only after the IO's validation on the deliverable of To-Cost Design Optimization.



## 5. Additional Notes and Disclaimer

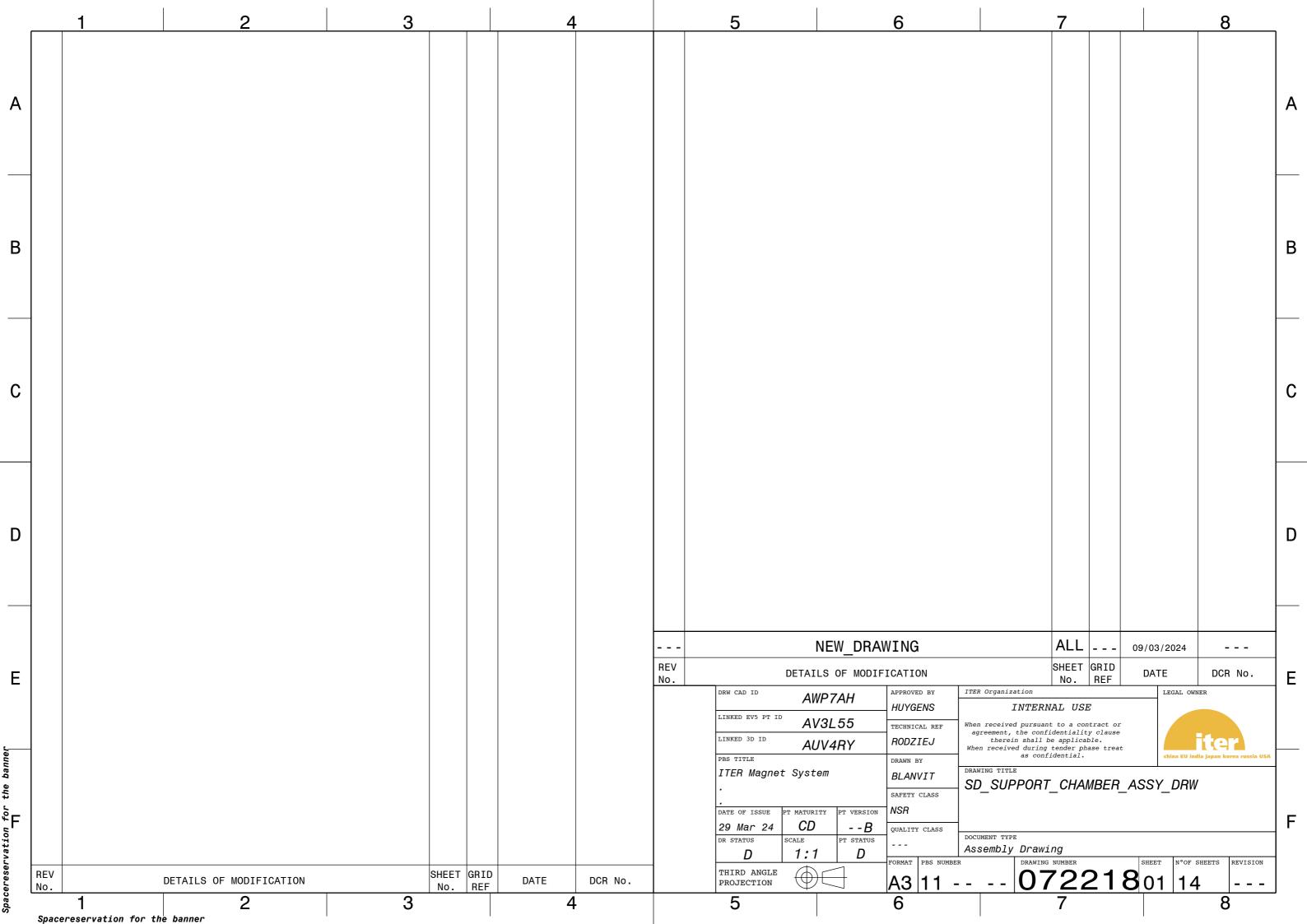
- Please send any questions regarding the survey to the contact given in the cover letter via email. The received questions and their answers may be published in a manner that does not identify the questioner.
- If there will be any additional information and modifications to this Market Survey, they will be published at the same web page.
- All information provided in this Market Survey is tentative and subject to change.
- All intellectual property rights and other rights related to the information provided in this survey belong to the IO. Participants in the survey and viewers of the information are permitted to use the obtained information solely for the purpose of preparing responses to the survey and must not use it for any other purposes.
- Participation in this survey does not automatically grant eligibility for future procurement processes. Eligibility for future procurement procedures remains undetermined.

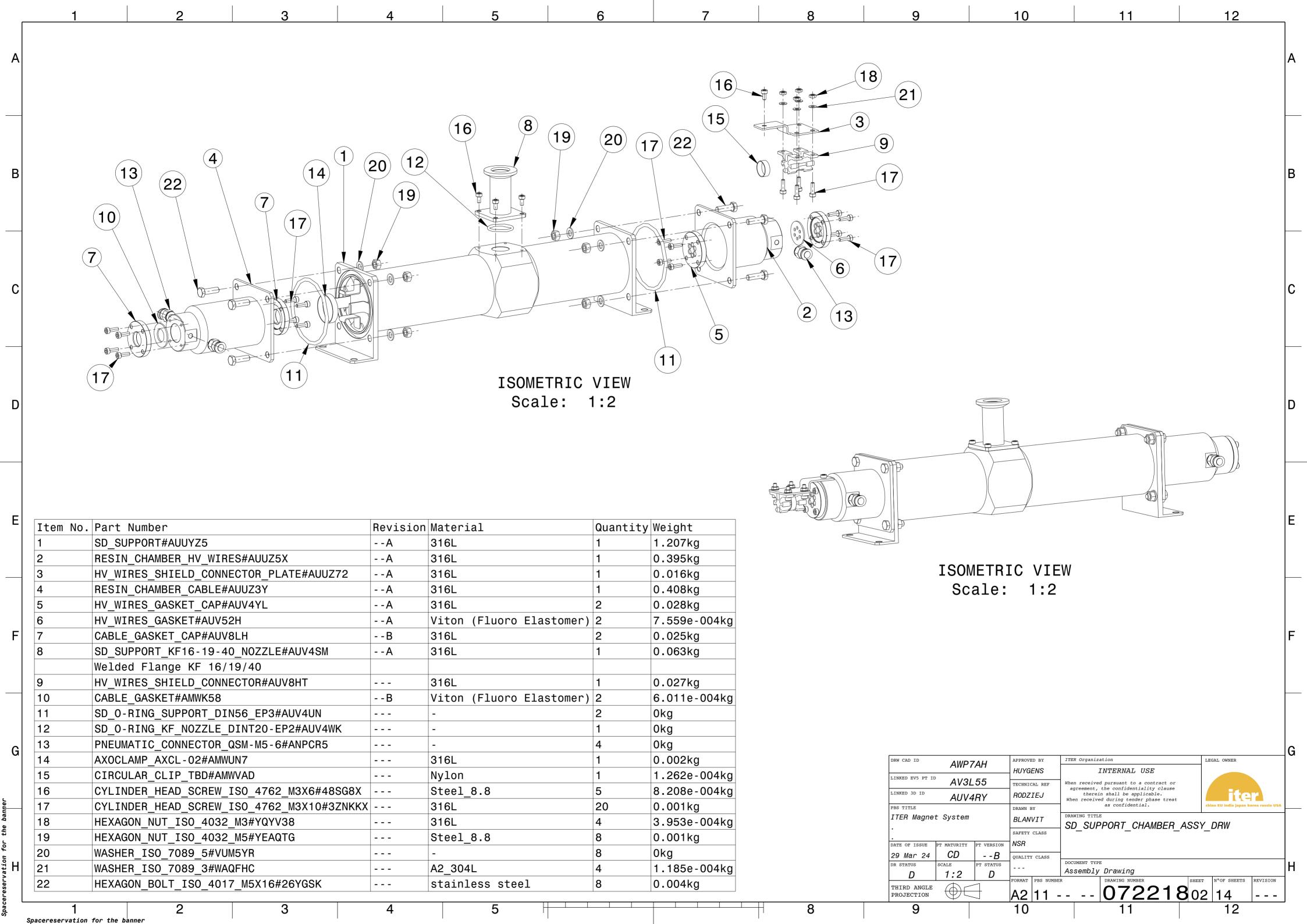
Annex-I

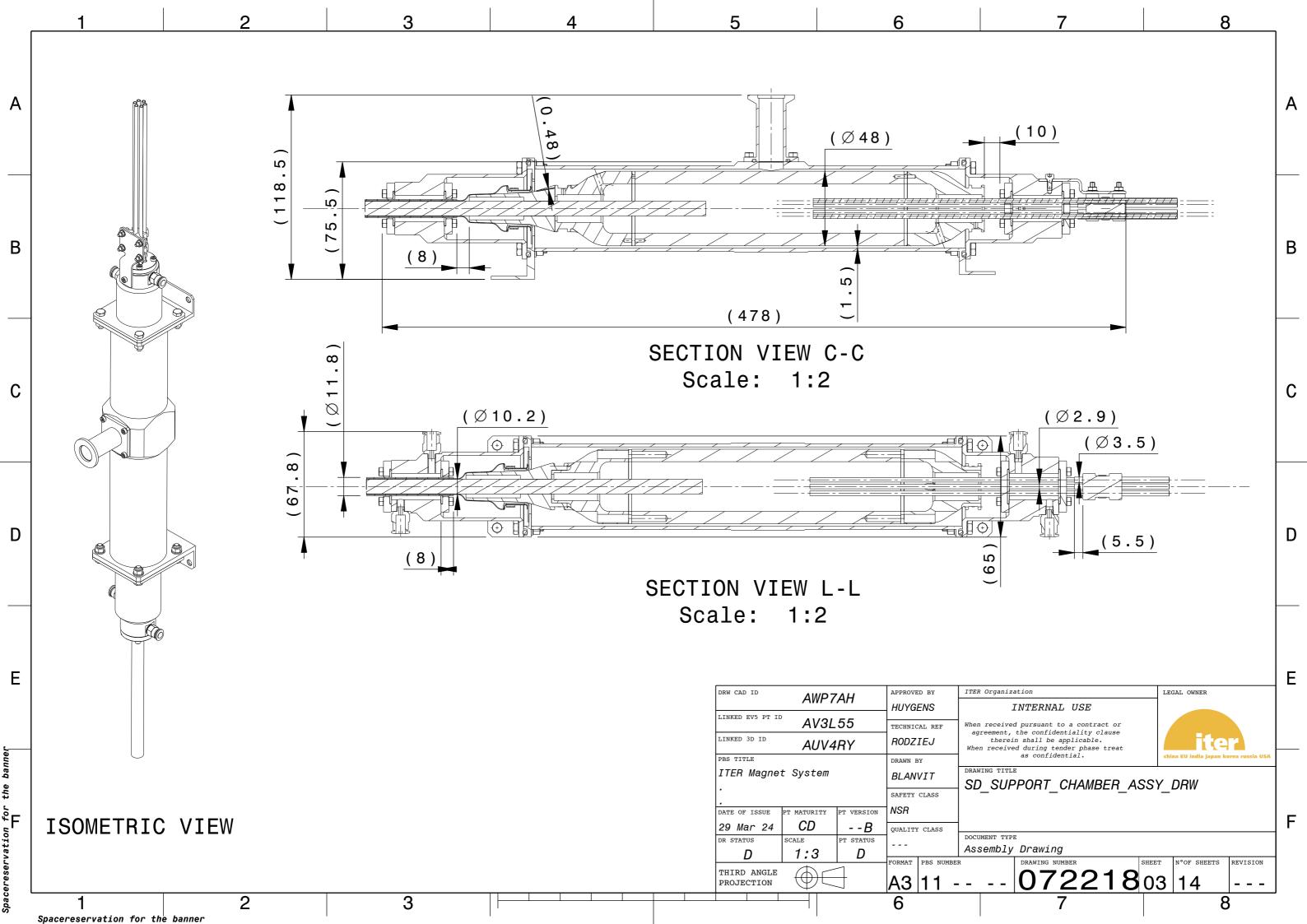
## Attachment

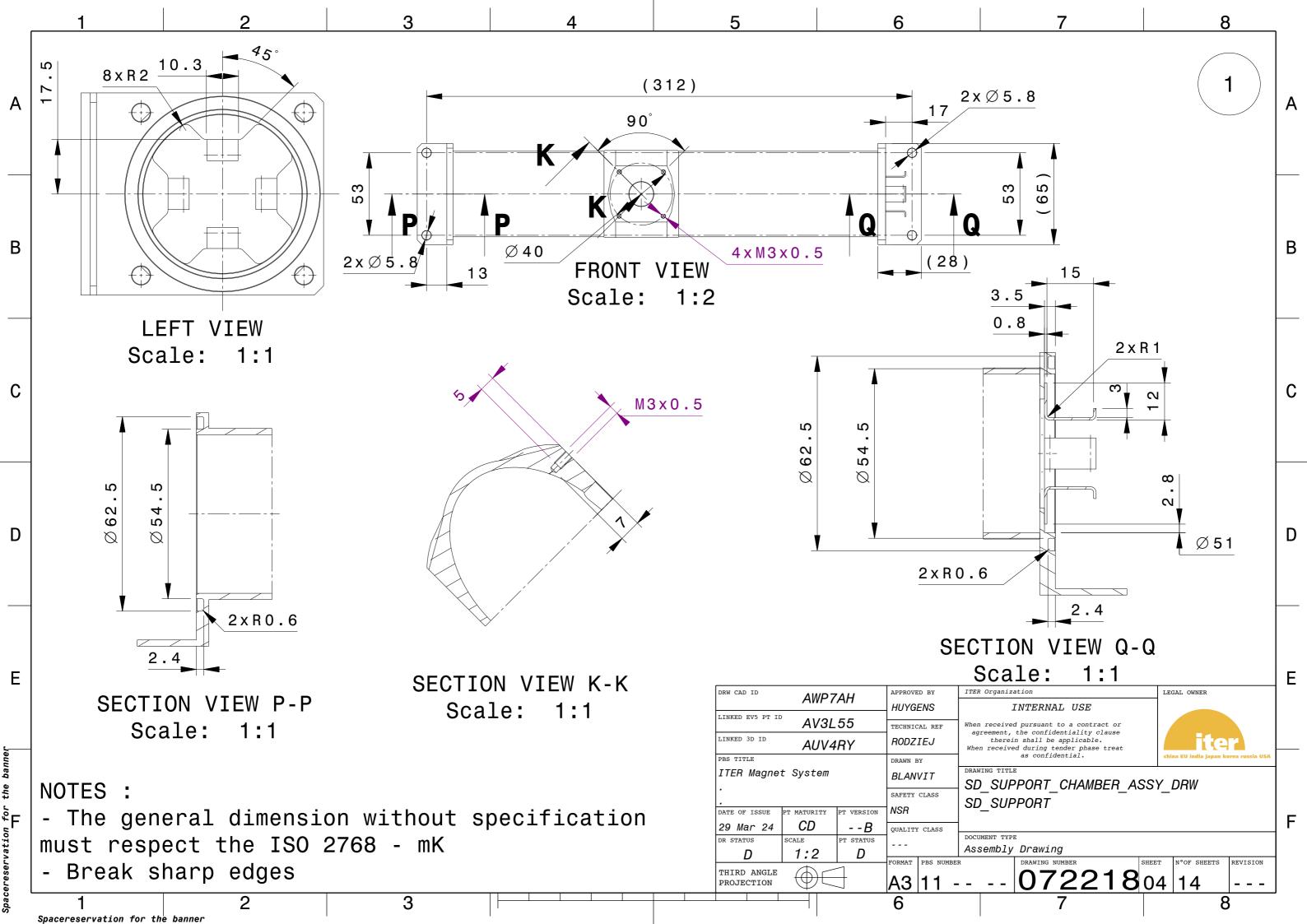
Appendix-1: Preliminary Design Drawing

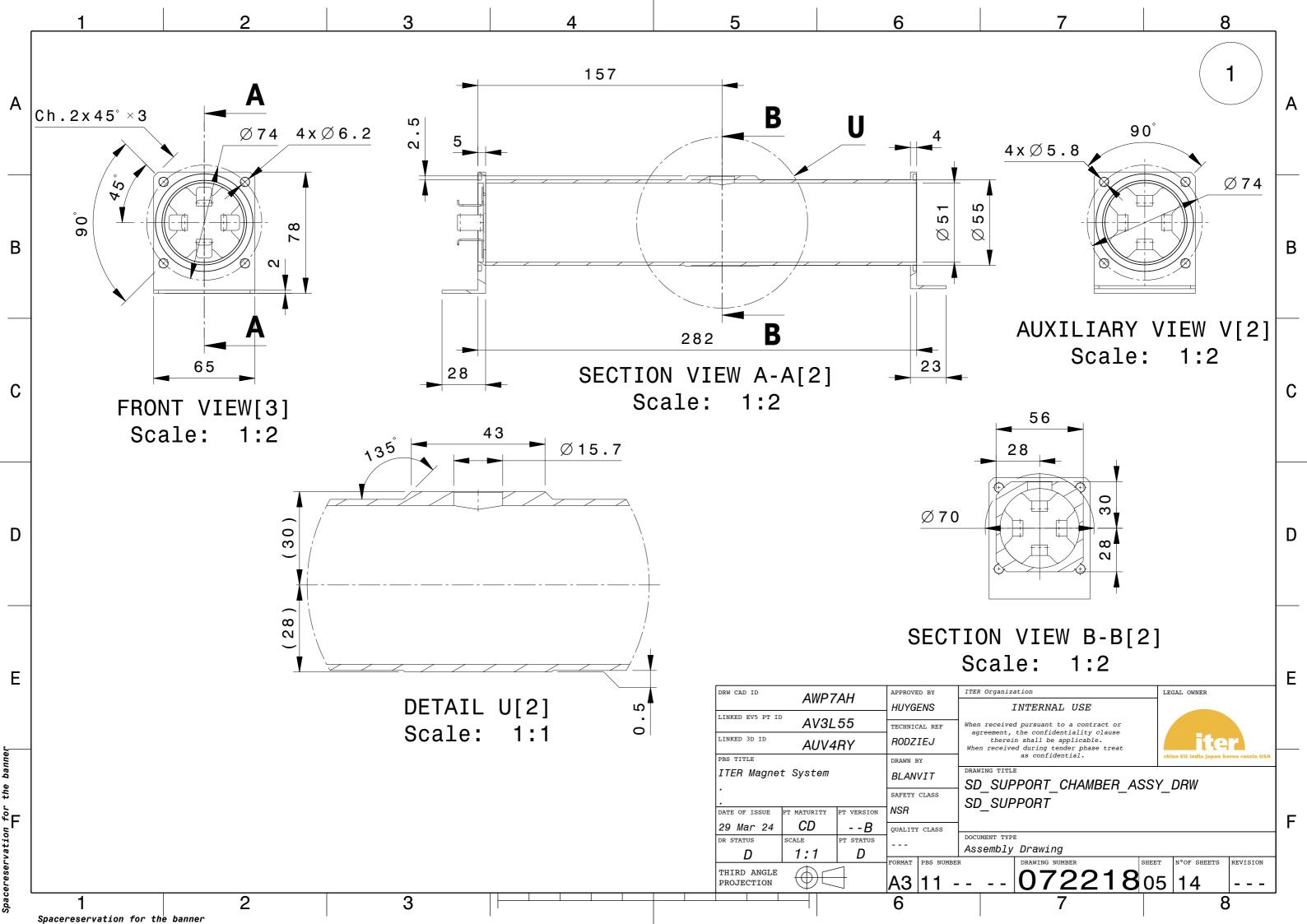
Appendix-2: 3D model data of Preliminary Design

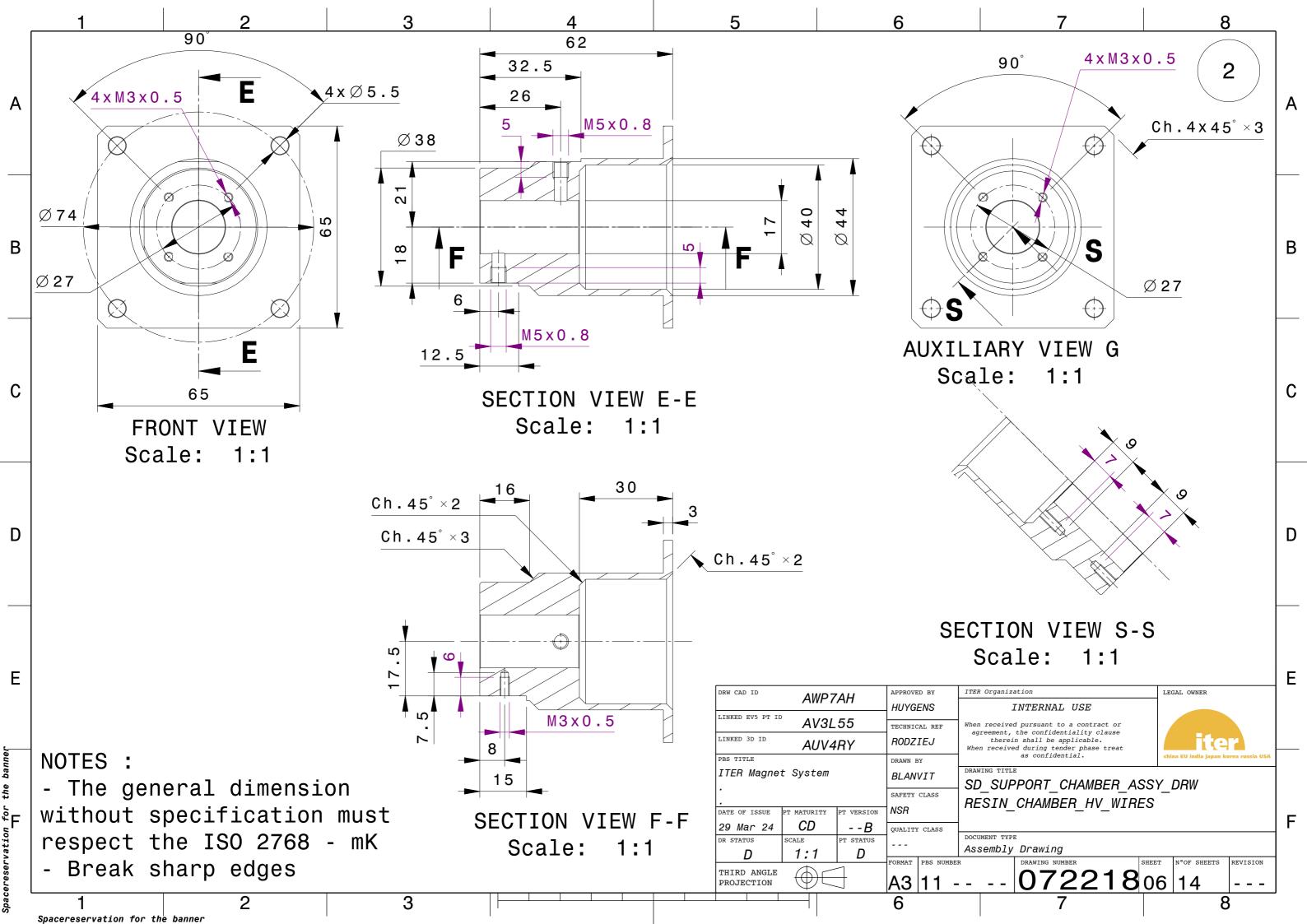


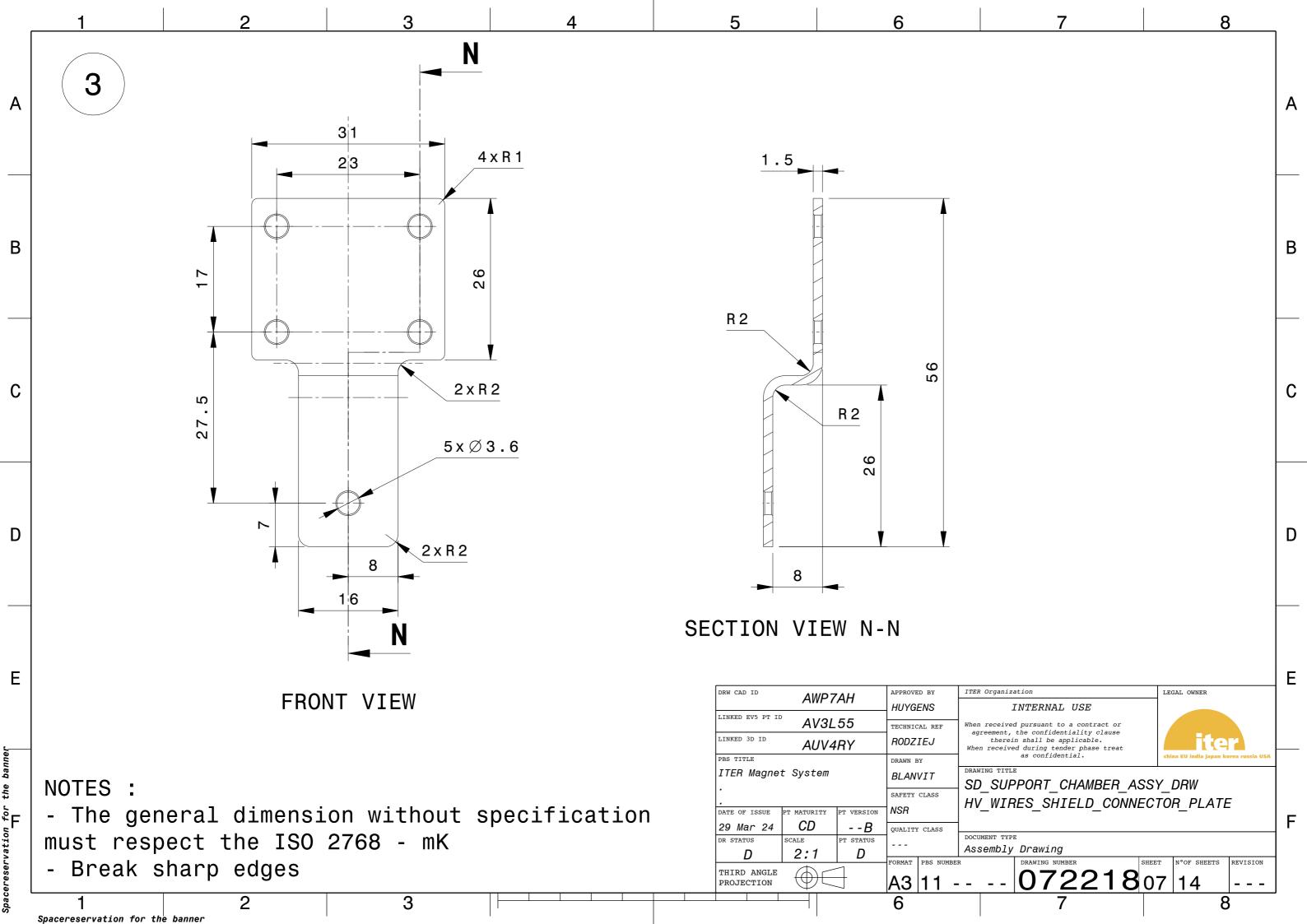


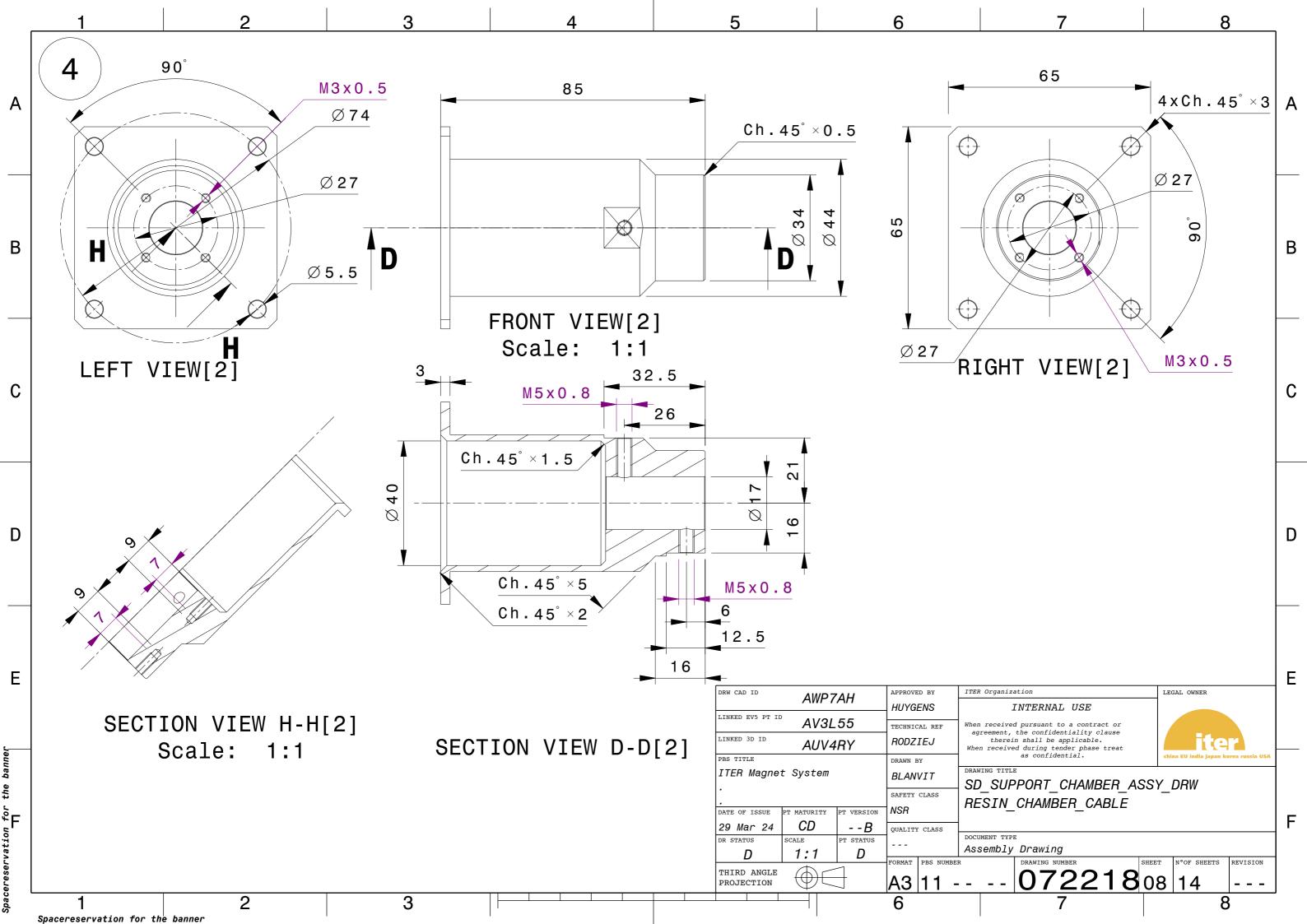


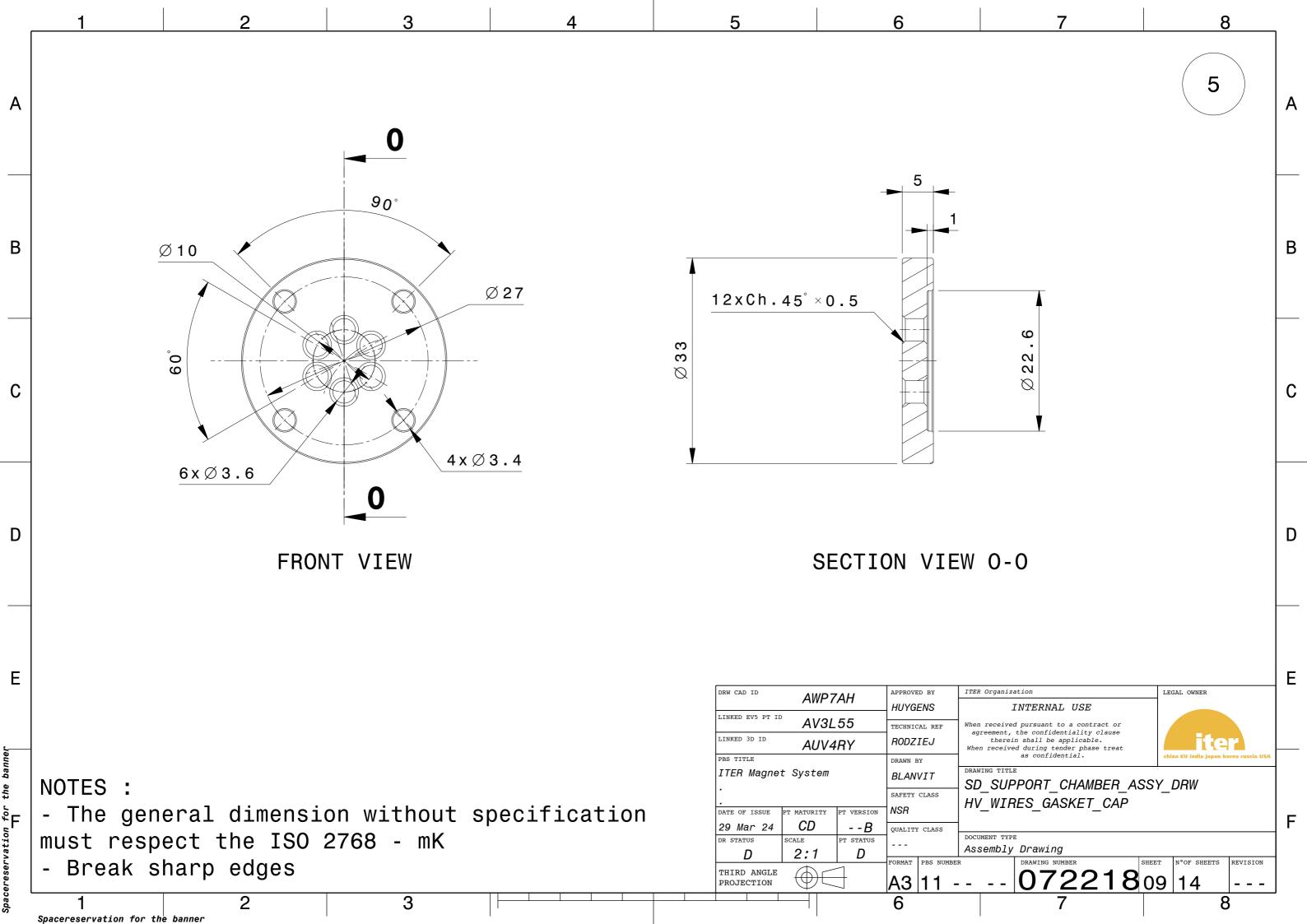


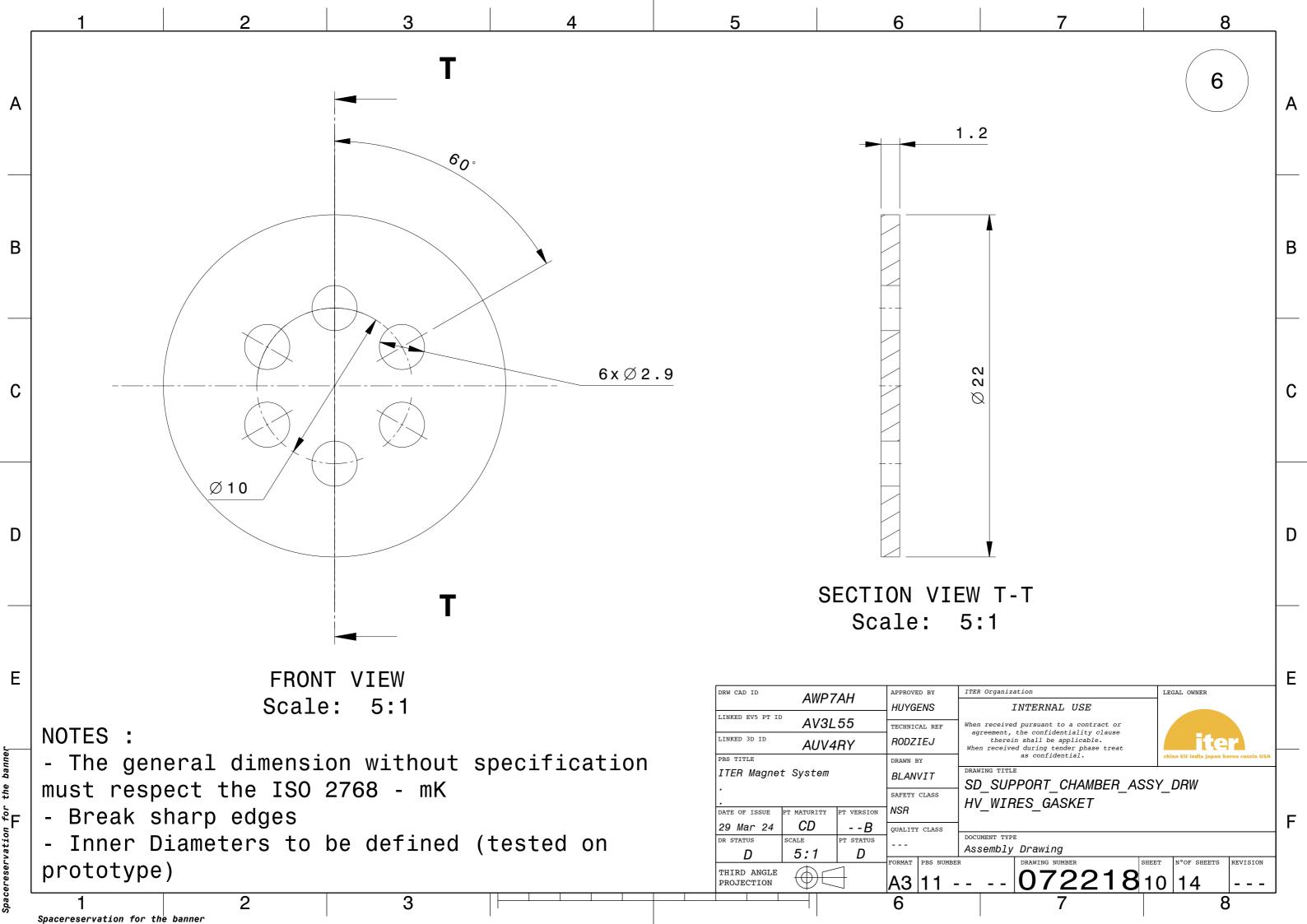


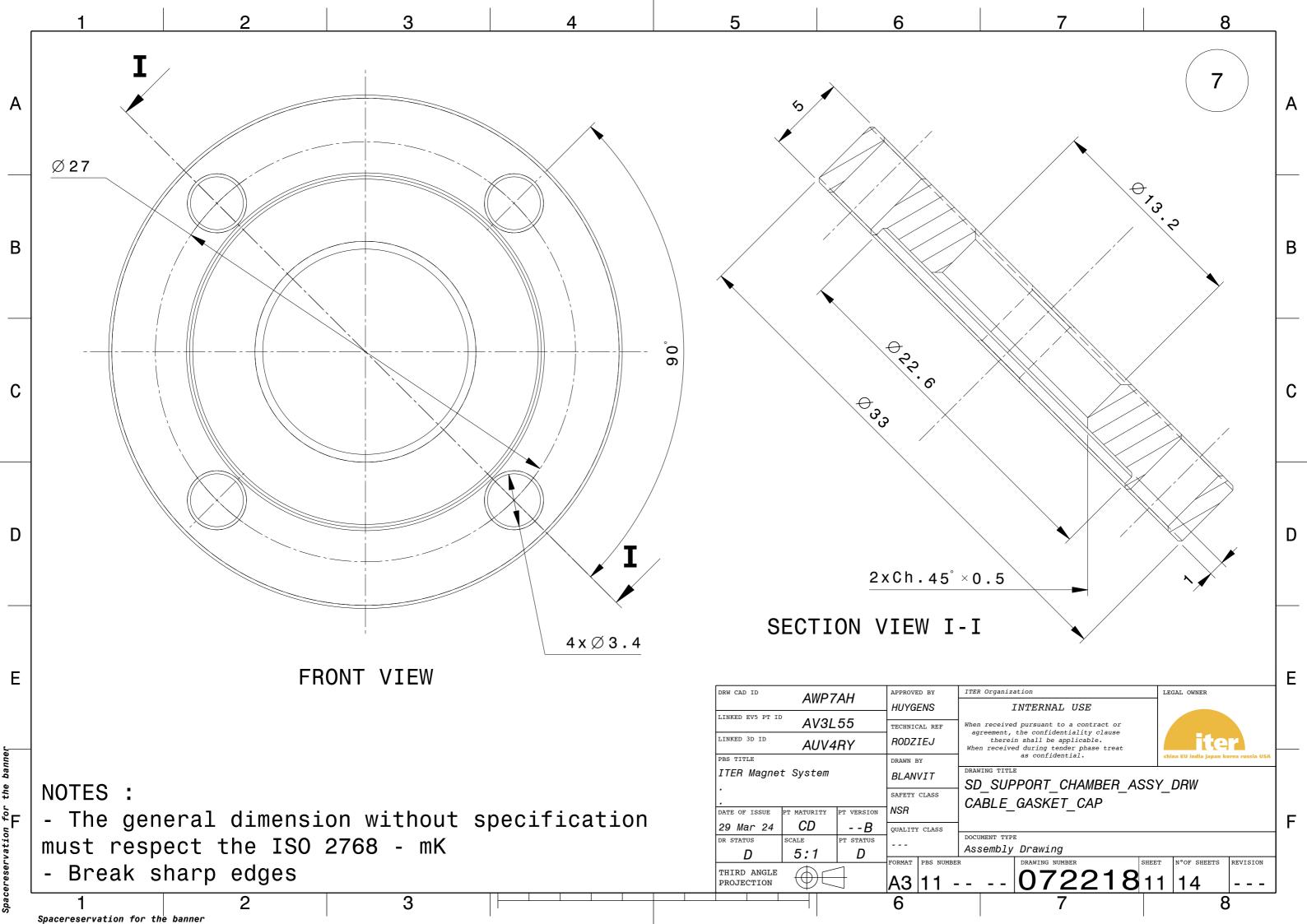


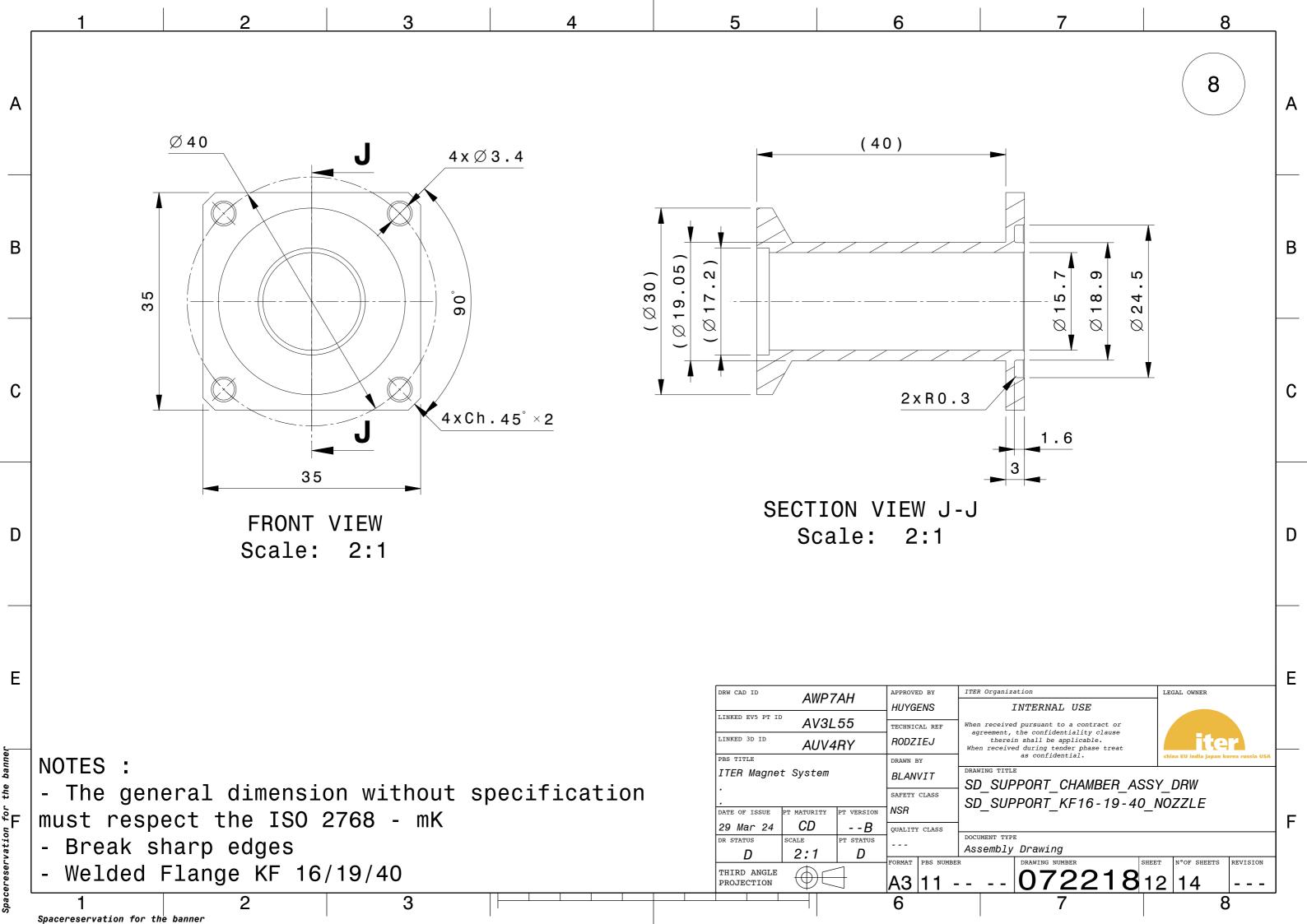


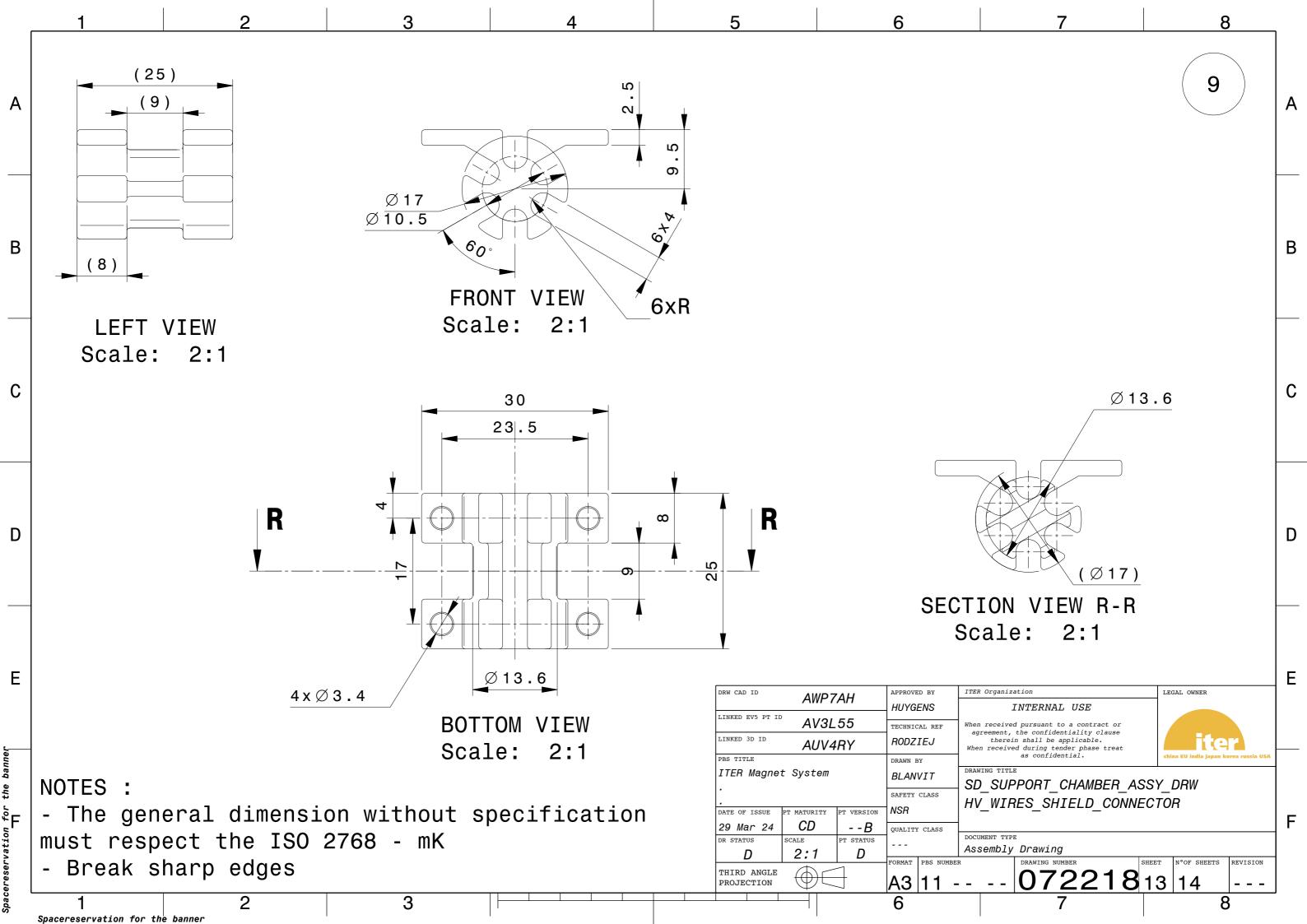


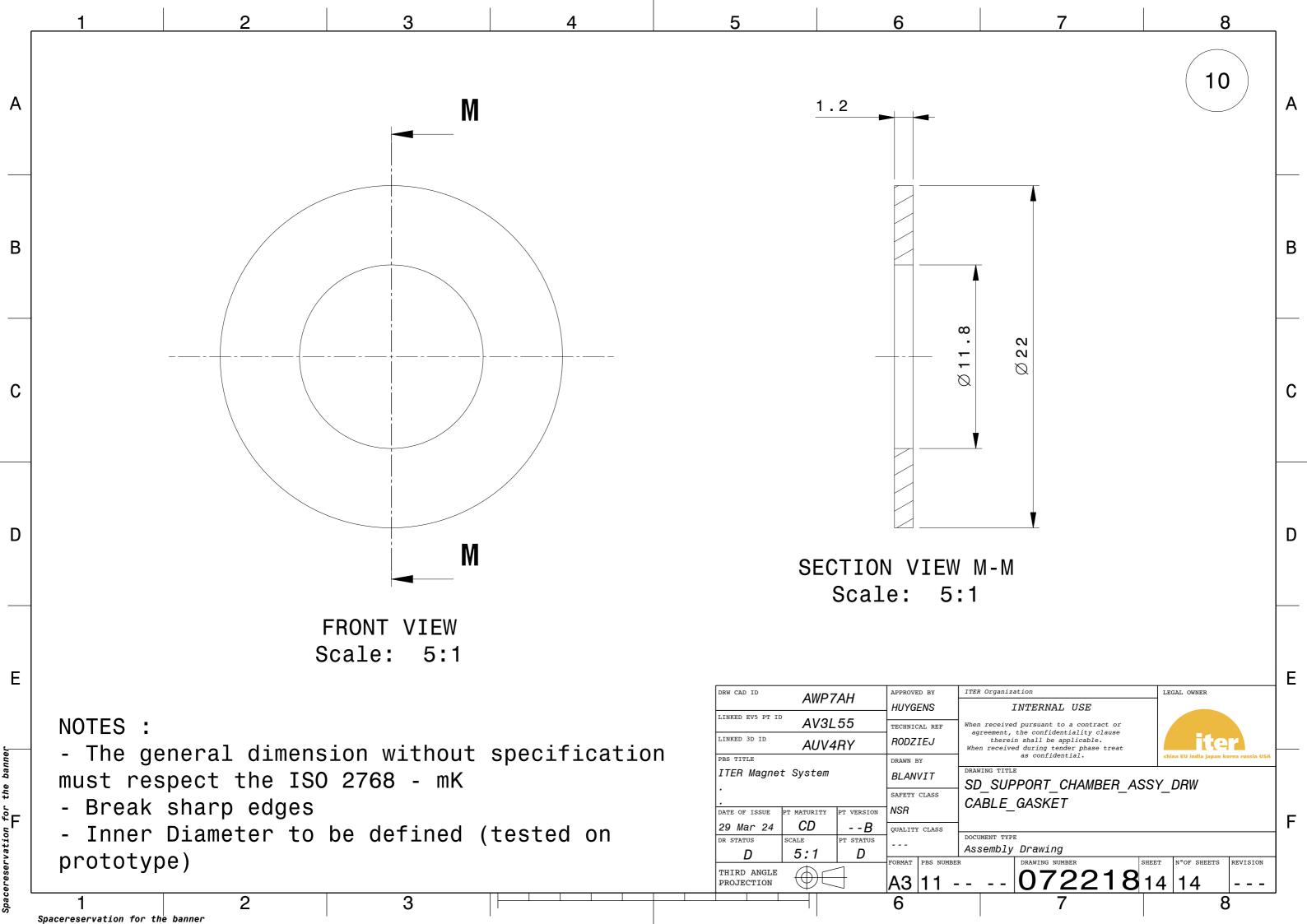
















## Annex II – Request for Information (RFI) Questionnaire

#### Ref. IO/MS/25/YSA/SA

## **Splicer Assembly - Market Survey**

Please return a completed questionnaire, no later than 24 February 2025, to the following email address <u>Yuki.Suyama@iter.org</u> with CC to <u>Guillaume.Retaillaud@iter.org</u>.

Due to mailing system reason, when attaching a large file such as the company's brochure exceeding 20MB, please use a cloud service or other means.

## 1. General information about the Company / Institute compiling the questionnaire

China, India, the Republic of Korea, the Russian Federation and the USA) are eligible for participating this procurement.

General information	
Company / Institute Name	
Nationality*	
Principle Adress	
Years in Operation	
Web site URL	
* Companies/Institutions/Entities established	within an ITER Member State (the European Union, Japan, the People's Republic of

china

Contact Information

india

japan

korea

russia

 Contact person
 Name + Title
 Email address
 Telephone

 Commercial Matters:
 +

 Technical Matters:
 +

**Primary Industrial Focus** 

Main activities	Description
1	
2	
3	

Turnover of recent three years and Workforce

Please indicate the year	Turnover 202X	Turnover 202X	Turnover 202X	Number of employees
All activities				
In the field of design and/or manufacturing of similar product				



	y A - Technical Competence		
•	u have any past experience for high-voltage connection	0 0	for manufacturing similar products mbers)?"
YES		NO	
-	e provide a brief overview o ate your expertise in this are	-	nd/or examples of past projects/contract
22 Arox	ou certified ISO 9001 or e	auivalant?	
2.2 Ale y	ou certified 150 5001 of ea	quivalent:	
YES		NO	
Please	specify your certifications i	relating to Quality	Assurance.
Quality Assi	urance Certifications	Comments	
4.4 PJ			
Please	e provide information that december also attach the company's leacturing capacity (if any).	•	manufacturing capacity.  materials introducing your products and
a) Main	location of manufacturing f	facility (City, Cou	ntry)
	products and the manufactural facturing quantity per mont		. Name of products, maximum
c) Name	e of the port for shipping the	product (if applic	cable)



d) Other	r information demonstrating your manufacturing capacity
,	ou have capacity to manufacture the product object for this Market Survey (i.e. er Assembly)?
YES	[ (if Yes, please answer the following) NO [
i) M	Manufacturing capacity (e.g. No. of units per month)
ii) P	art of works to be subcontracted (if any, specify)
iii) A	any other information demonstrating manufacturing capacity of Splicer Assembly
any po achiev how y	e specified technical requirements, excluding To-Cost Design Optimization, are there carticular specifications or requirements that you consider especially challenging to be? If so, please identify these areas and explain the potential obstacles, as well as your team would approach addressing these challenges during the design and facturing phases
YES	□ NO □
If YES, please and counterm	e identify these areas and explain the potential obstacles, as well as possible solutions easures.



### 3. Survey B - Pricing and Procurement

3.1 Please provide your non-binding price estimation for manufacturing of the following deliverables based on the IO's preliminary design as per attached drawing of the kit #072218 (Annex-I, Appendix-1). The price shall be quoted in EUR per unit, shall include packing cost for shipment and shall not include VAT and customs duties. The Price shall be quoted on Incoterms 2020 EX Works (EXW) basis. If available, please also provide the price on Incoterms 2020 Delivered at Place (DAP) – the IO site basis.

No.	Deliverable	Planned Overall Quantity	Timeline (T0=Contract signature)	Price per unit EXW (EUR)	Price per unit DAP-IO Site (EUR), if available
a)	Splicer Assemblies (Pre-series manufacturing)	18 units	T0 + 6 Months		
b)	Splicer Assemblies (Series manufacturing)	450 units	T0 + 15 Months		

indicate belo	w the assumptions and/or conditions for the above pricing, if any.
series produ nt of the supp n Optimizatio	nnex-I, the preliminary design of the Splicer Assembly must be optimized action, to meet the target price of below 1kEUR per unit by taking into plier's manufacturing facility and its work method to be taken (To-cost on). The scope of this work will be limited to non-physical design only, and 2D drawing serving as the basis for evaluation by IO.
u think your	company is capable to do this To-cost Design Optimization work?
	NO
IO's evaluati	essary work duration to complete the To-cost Design Optimization on and validation time. Also please provide estimated cost for this work. or To-cost Design Optimization
	ntioned in An e series produ nt of the supp n Optimizatio he 3D model o u think your o  c provide nece IO's evaluati



Nece	essary work duration for	To-cost Des	sign Optimizatio	n (in month) :	
(Plea	nated cost for To-cost Dose provide cost elements bove amount)		•		), as justification of
If NO	, please provide the reason	on or any co	omment.		
3	3 Please provide your i deliverables based on	-	-	on for manufactu	uring of the following
	#072218. The price s shipment and shall no	hall be qu t include V	oted in EUR po AT and customs	er unit, shall inc duties. The trans	ed drawing of the kin lude packing cost for port to the IO site and
No.	#072218. The price s	hall be quent include Vers marine ins	oted in EUR por AT and customs surance shall be Timeline (T0=Contract	er unit, shall inc duties. The trans	ed drawing of the kindle packing cost for port to the IO site and if available.  Transport cost per unit (EUR), if
<b>No.</b> a)	#072218. The price s shipment and shall no associated cost_such as	hall be quent include Versions in the second	oted in EUR po AT and customs surance shall be Timeline	er unit, shall incest duties. The transes separately quoted.  Price per unit	ed drawing of the kindle lude packing cost for port to the IO site and if available.  Transport cost
	#072218. The price s shipment and shall no associated cost_such as  Deliverable  Splicer Assemblies (Pre-series	hall be quent include Verante include Verall Quantity	AT and customs surance shall be Timeline (T0=Contract signature)	er unit, shall incest duties. The transes separately quoted.  Price per unit	ed drawing of the kindle packing cost for port to the IO site and if available.  Transport cost per unit (EUR), if
a)	#072218. The price s shipment and shall no associated cost_such as  Deliverable  Splicer Assemblies (Pre-series manufacturing)  Splicer Assemblies	hall be quent include Vermarine instructions  Planned Overall Quantity  18 units	Timeline (T0=Contract signature) T0 + 6 Months T0 + 15 Months	er unit, shall inc s duties. The trans s separately quoted Price per unit (EUR)	ed drawing of the kindle packing cost for port to the IO site and if available.  Transport cost per unit (EUR), if available
a)	#072218. The price s shipment and shall no associated cost_such as  Deliverable  Splicer Assemblies (Pre-series manufacturing)  Splicer Assemblies (Series manufacturing)	hall be quent include Vermarine instructions  Planned Overall Quantity  18 units	Timeline (T0=Contract signature) T0 + 6 Months T0 + 15 Months	er unit, shall inc s duties. The trans s separately quoted Price per unit (EUR)	ed drawing of the kindle packing cost for port to the IO site and if available.  Transport cost per unit (EUR), if available



## 4. General Comments

Please indicate any other information that may be relevant for this market survey.

Thank you very much for your valuable feedback!